

LH5268A

CMOS 64K (8K × 8) Static RAM

FEATURES

- 8,192 × 8 bit organization
- Access time: 100 ns (MAX.)
- Power consumption:
 - Operating:
 - 220 mW (MAX.)
 - 55 mW (MAX.) (t_{RC} , $t_{WC} = 1 \mu s$)
 - Standby:
 - 220 μW (MAX.)
 - Data retention:
 - 3.0 μW ($V_{CC} = 3 V$, $T_A = 25^\circ C$)
- Fully-static operation
- Three-state outputs
- Single +5 V power supply
- TTL compatible I/O
- Packages:
 - 28-pin, 600-mil DIP
 - 28-pin, 300-mil SK-DIP
 - 28-pin, 450-mil SOP

DESCRIPTION

The LH5268A is a static RAM organized as 8,192 × 8 bits. It is fabricated using silicon-gate CMOS process technology.

PIN CONNECTIONS

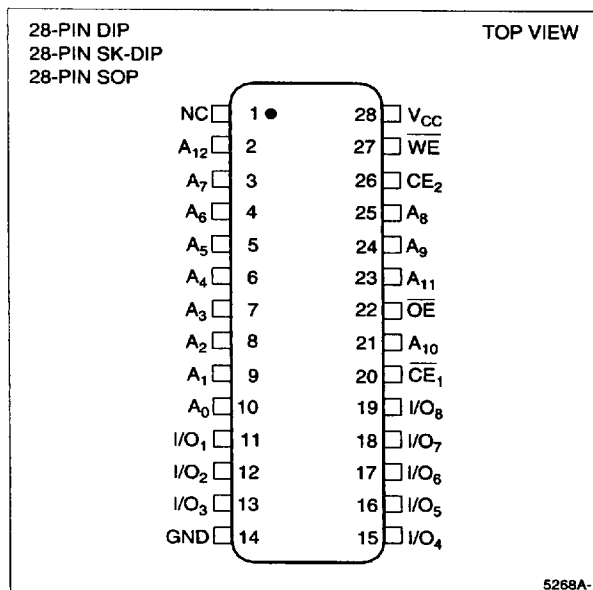


Figure 1. Pin Connections for DIP, SK-DIP, and SOP Packages

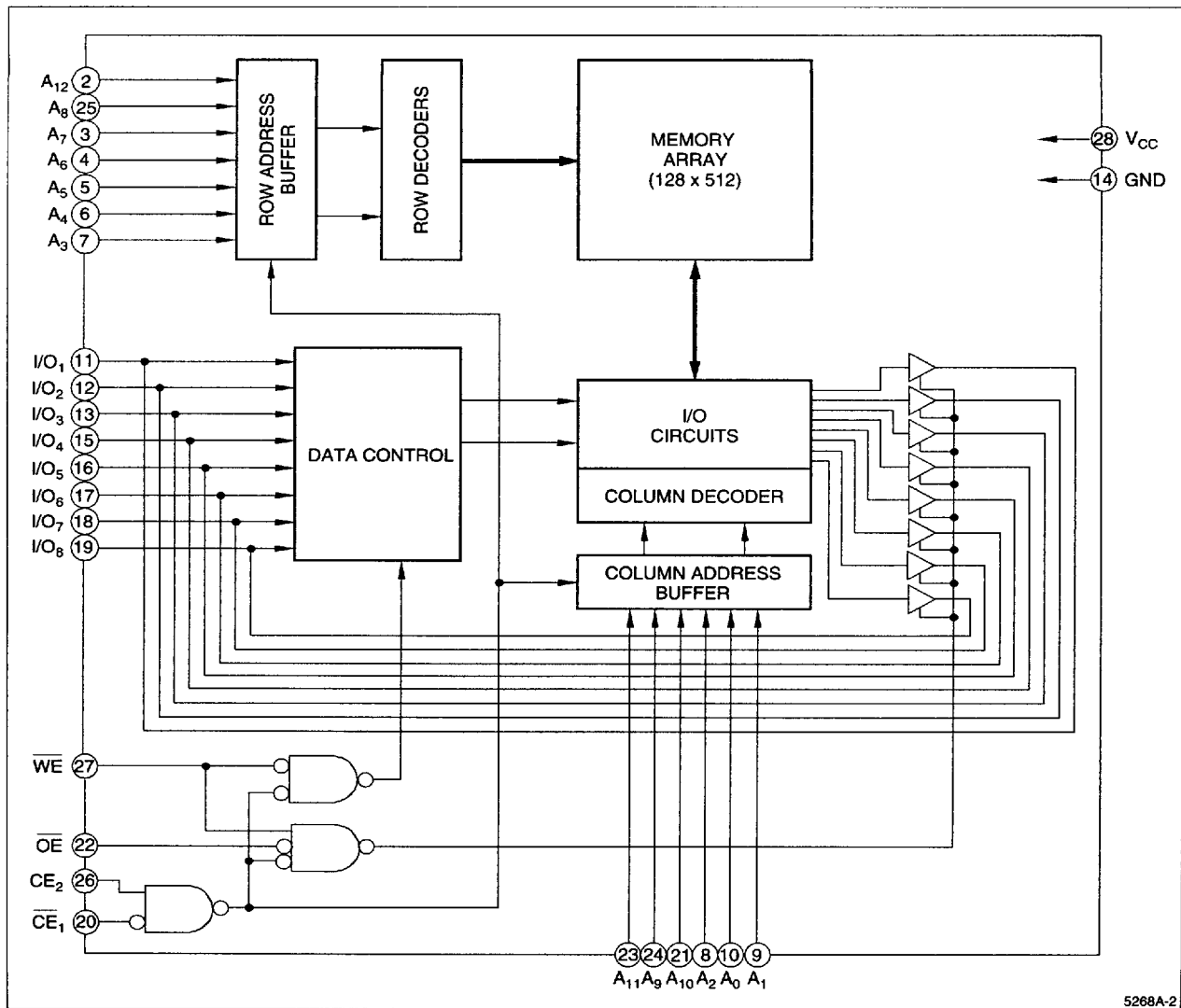


Figure 2. LH5268A Block Diagram

PIN DESCRIPTION

SIGNAL	PIN NAME	SIGNAL	PIN NAME
A ₀ - A ₁₂	Address inputs	I/O ₁ - I/O ₈	Data inputs and outputs
CE ₁ - CE ₂	Chip Enable input	V _{CC}	Power supply
WE	Write Enable input	GND	Ground
OE	Output Enable input	NC	No connection

TRUTH TABLE

$\overline{CE}_1$	CE_2	$\overline{WE}$	$\overline{OE}$	MODE	I/O ₁ - I/O ₈	SUPPLY CURRENT	NOTE
H	X	X	X	Deselect	High-Z	Standby (I_{SB})	1
X	L	X	X	Deselect	High-Z	Standby (I_{SB})	1
L	H	L	X	Write	D _{IN}	Operating (I_{CC})	1
L	H	H	L	Read	D _{OUT}	Operating (I_{CC})	
L	H	H	H	Output disable	High-Z	Operating (I_{CC})	

NOTE:

1. X = H or L

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT	NOTE
Supply voltage	V_{CC}	-0.3 to +7.0	V	1
Input voltage	V_{IN}	-0.3 to $V_{CC} + 0.3$	V	1,2
Operating temperature	T_{opr}	0 to +70	°C	
Storage temperature	T_{stg}	-65 to +150	°C	

NOTES:

1. The maximum applicable voltage on any pin with respect to GND.
 2. V_{IN} (MIN.) = -3.0 V for pulse width ≤ 50 ns.

RECOMMENDED OPERATING CONDITIONS ($T_A = 0$ to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
Supply voltage	V_{CC}	4.5	5.0	5.5	V	
Input voltage	V_{IH}	2.2		$V_{CC} + 0.3$	V	
	V_{IL}	-0.3		0.8	V	1

NOTE:

1. V_{IN} (MIN.) = -3.0 V for pulse width ≤ 50 ns.

DC CHARACTERISTICS ($T_A = 0$ to +70°C, $V_{CC} = 5\text{ V} \pm 10\%$)

PARAMETER	SYMBOL	CONDITIONS	MIN.	MAX.	UNIT	NOTE
Input leakage current	I_{LI}	$V_{IN} = 0$ to V_{CC}	-1	1	μA	
Output leakage current	I_{LO}	$CE_1 = V_{IH}$ or $CE_2 = V_{IL}$ or $OE = V_{IH}$ or $WE = V_{IL}$ $V_{I/O} = 0$ V to V_{CC}	-1	1	μA	
Operating current	I_{CC}	$CE_1 = V_{IL}$, $V_{IN} = V_{IL}$ or V_{IH} $CE_2 = V_{IH}$, $I_{I/O} = 0$ mA $t_{CYCLE} = 100$ ns		40	mA	
		$CE_1 = 0.2$ V, $V_{IN} = 0.2$ V or $V_{CC} - 0.2$ V $CE_2 = V_{CC} - 0.2$ V, $I_{I/O} = 0$ mA $t_{CYCLE} = 1.0$ μs		10	mA	
Standby current	I_{SB1}	$CE_1 = V_{IH}$ or $CE_2 = V_{IL}$		3	mA	
	I_{SB}	$CE_2 \leq 0.2$ V or $CE_1 \geq V_{CC} - 0.2$ V		40	μA	1
Output voltage	V_{OL}	$I_{OL} = 2.1$ mA		0.4	V	
	V_{OH}	$I_{OH} = -1.0$ mA	2.4		V	

NOTE:

1. CE_2 should be $\geq V_{CC} - 0.2$ V or ≤ 0.2 V when $CE_1 \geq V_{CC} - 0.2$ V.

AC CHARACTERISTICS

(1) READ CYCLE ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Read cycle time	t_{RC}	100		ns	
Address access time	t_{AA}		100	ns	
Chip enable (CE ₁) access time	t_{ACE1}		100	ns	
(CE ₂)	t_{ACE2}		100	ns	
Output enable access time	t_{OE}		40	ns	
Output hold time	t_{OH}	10		ns	
Chip enable to output in Low-Z (CE ₁)	t_{LZ1}	10		ns	1
(CE ₂)	t_{LZ2}	10		ns	1
Output enable to output in Low-Z	t_{OLZ}	5		ns	1
Chip enable to output in High-Z (CE ₁)	t_{HZ1}	0	30	ns	1
(CE ₂)	t_{HZ2}	0	30	ns	1
Output disable to output in High-Z	t_{OHZ}	0	20	ns	1

NOTE:

- Active output to high-impedance and high-impedance to output active tests specified for a ± 200 mV transition from steady state levels into the test load.

(2) WRITE CYCLE ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Write cycle time	t_{WC}	100		ns	
Chip enable to end of write	t_{CW}	80		ns	
Address valid to end of write	t_{AW}	80		ns	
Address setup time	t_{AS}	0		ns	
Write pulse width	t_{WP}	60		ns	
Write recovery time	t_{WR}	0		ns	
Data valid to end of write	t_{DW}	40		ns	
Data hold time	t_{DH}	0		ns	
Output active from end of write	t_{OW}	10		ns	1
WE to output in High-Z	t_{WZ}	0	30	ns	1
OE to output in High-Z	t_{OHZ}	0	20	ns	1

NOTE:

- Active output to high-impedance and high-impedance to output active tests specified for a ± 200 mV transition from steady state levels into the test load.

AC TEST CONDITIONS

PARAMETER	MODE	NOTE
Input voltage amplitude	0.6 to 2.4 V	
Input rise/fall time	10 ns	
Timing reference level	1.5 V	
Output load conditions	1TTL + C _L (100 pF)	1

NOTE:

- Includes scope and jig capacitance.

CAPACITANCE ¹ ($T_A = 25^\circ\text{C}$, $f = 1\text{ MHz}$)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Input capacitance	C_{IN}	$V_{IN} = 0\text{ V}$			7	pF
Input/output capacitance	C_{IO}	$V_{IO} = 0\text{ V}$			10	pF

NOTE:

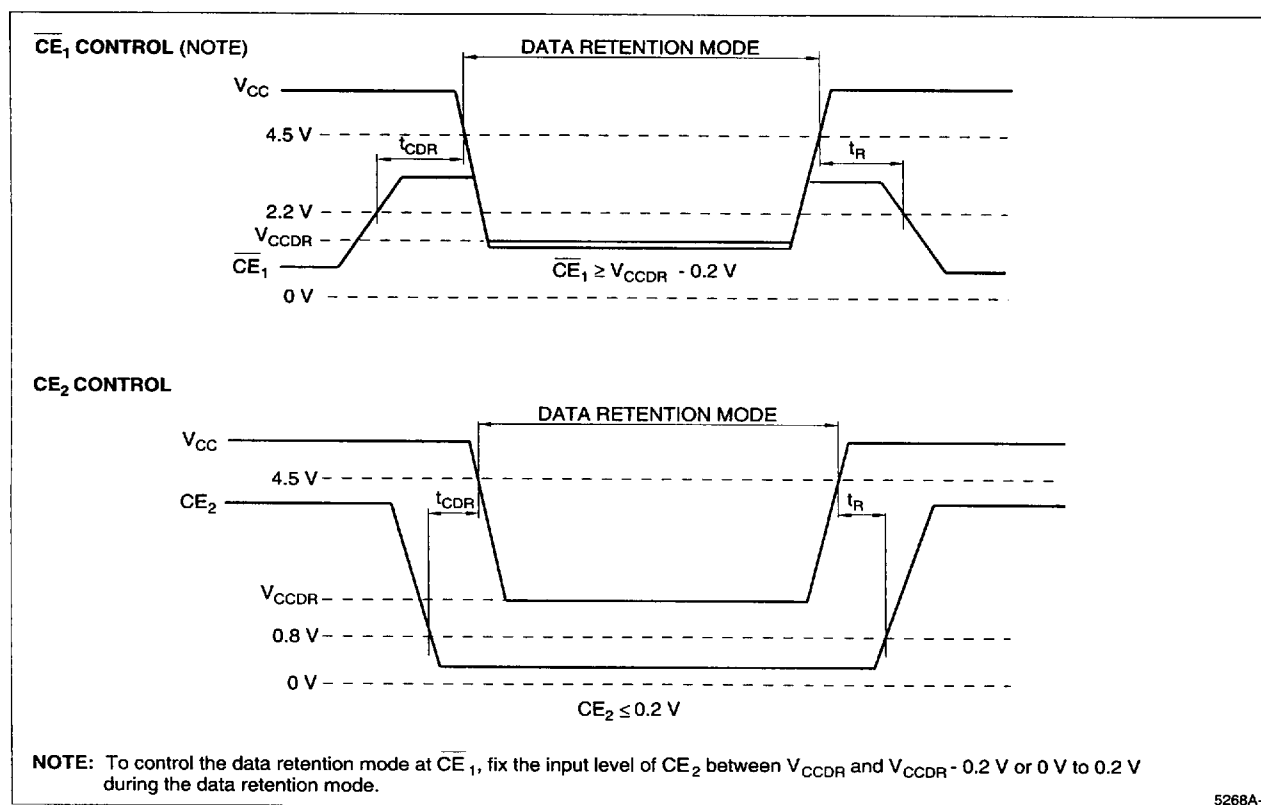
1. This parameter is sampled and not production tested.

DATA RETENTION CHARACTERISTICS ($T_A = 0$ to $+70^\circ\text{C}$)

PARAMETER	SYMBOL	CONDITIONS	MIN.	MAX.	UNIT	NOTE
Data retention voltage	V_{CCDR}	$CE_2 \leq 0.2\text{ V}$ or $CE_1 \geq V_{CCDR} - 0.2\text{ V}$	2.0	5.5	V	1
Data retention current	I_{CCDR}	$V_{CCDR} = 3\text{ V}$, $CE_2 \leq 0.2\text{ V}$ or $CE_1 \geq V_{CCDR} - 0.2\text{ V}$		1	μA	1
				20	μA	
Chip disable to data retention	t_{CDR}		0		ns	
Recovery time	t_R		t_{RC}		ns	2

NOTES:

1. CE_2 should be $\geq V_{CCDR} - 0.2\text{ V}$ or $\leq 0.2\text{ V}$ when $CE_1 \geq V_{CCDR} - 0.2\text{ V}$
2. t_{RC} = Read cycle time

**Figure 3. Low Voltage Data Retention**

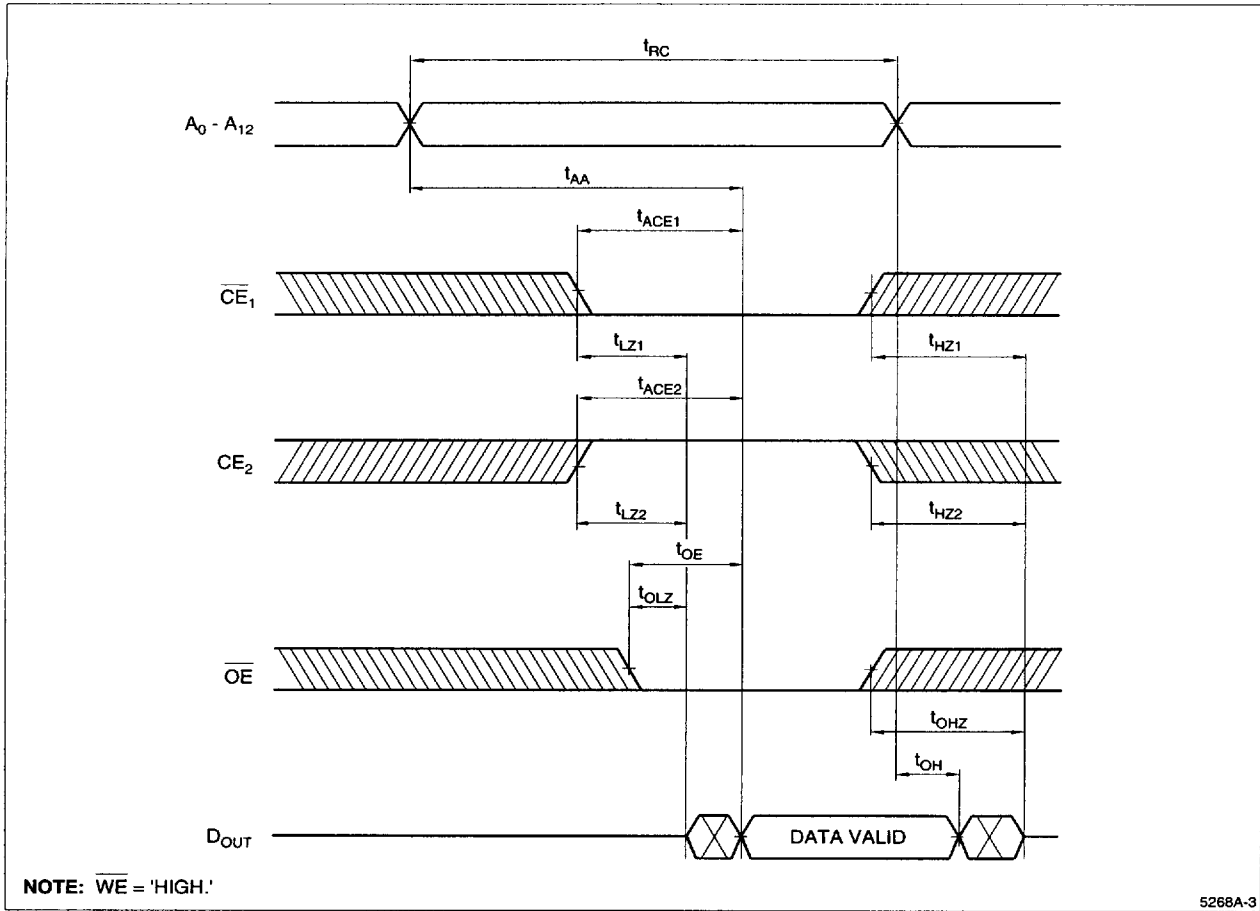
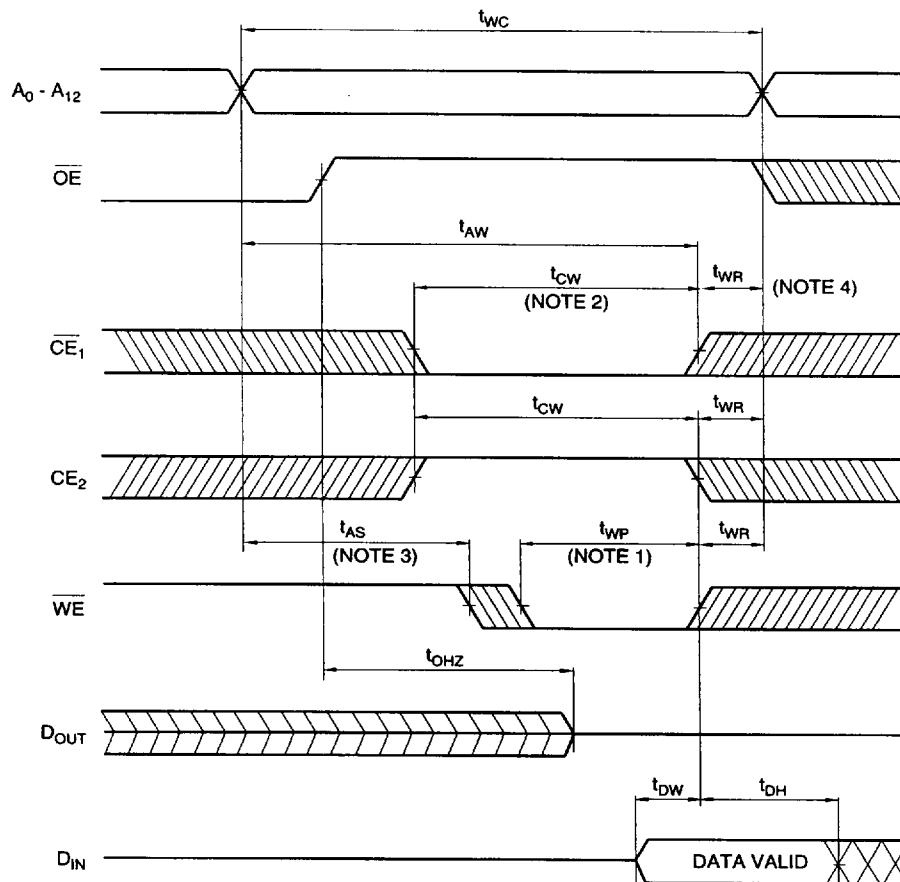


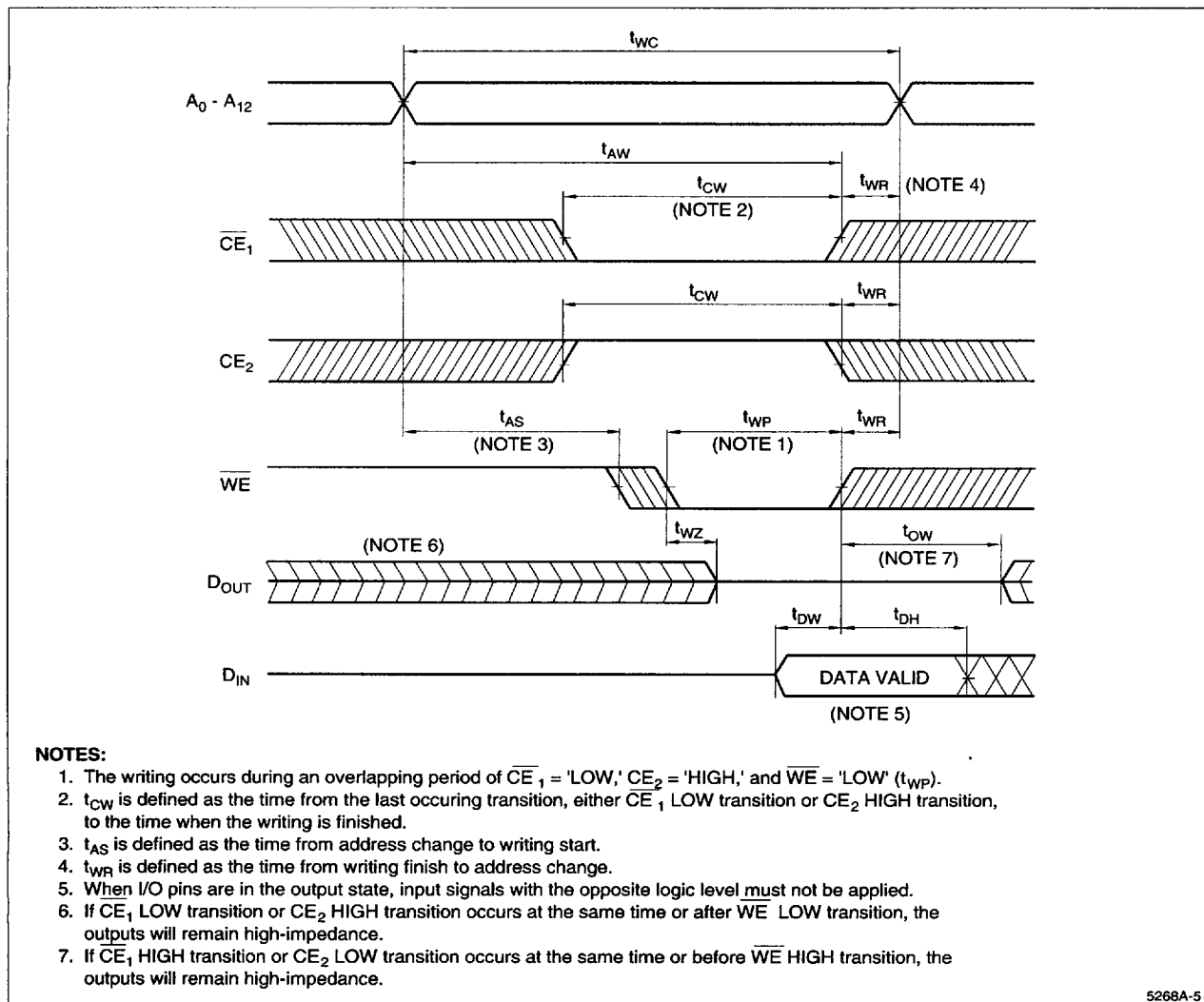
Figure 4. Read Cycle

**NOTES:**

1. The writing occurs during an overlapping period of $\overline{CE}_1 = \text{'LOW'}$, $CE_2 = \text{'HIGH'}$, and $\overline{WE} = \text{'LOW'}$ (t_{WP}).
2. t_{CW} is defined as the time from the last occurring transition, either $\overline{CE}_1$ LOW transition or CE_2 HIGH transition, to the time when the writing is finished.
3. t_{AS} is defined as the time from address change to writing start.
4. t_{WR} is defined as the time from writing finish to address change.

5268A-4

Figure 5. Write Cycle 1

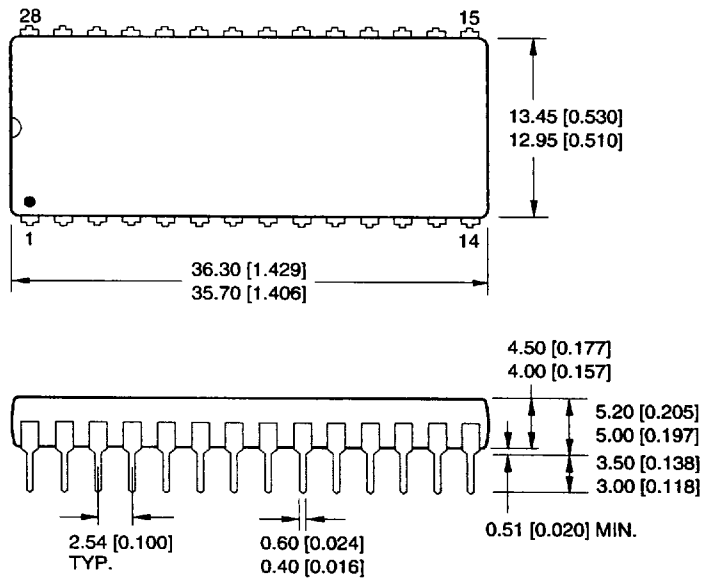


5268A-5

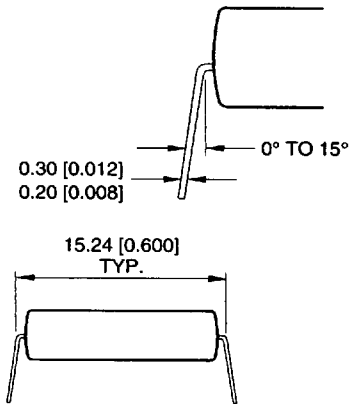
Figure 6. Write Cycle 2

PACKAGE DIAGRAMS

28DIP (DIP028-P-0600)



DETAIL

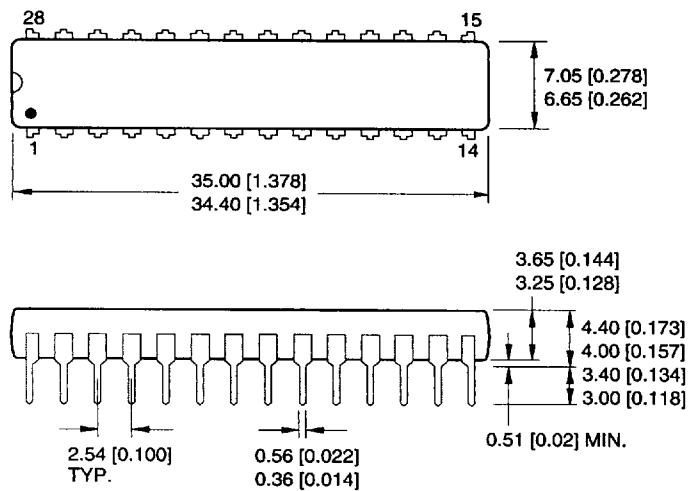


DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

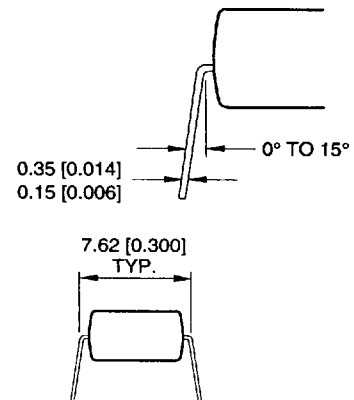
28DIP-2

28-pin, 600-mil DIP

28DIP (DIP028-P-0300)



DETAIL

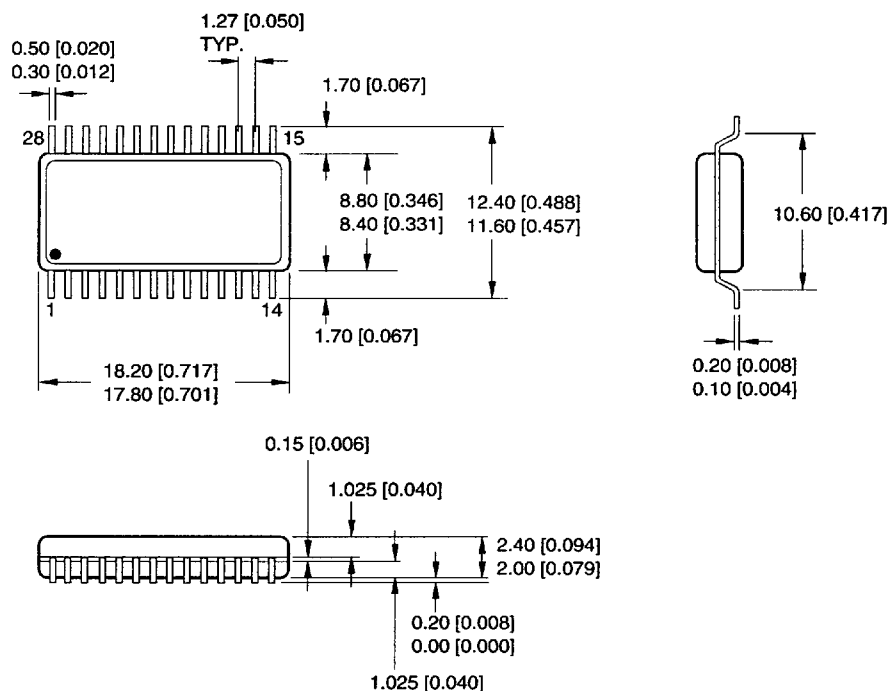


DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

28DIP-6

28-pin, 300-mil DIP

28SOP (SOP028-P-0450)

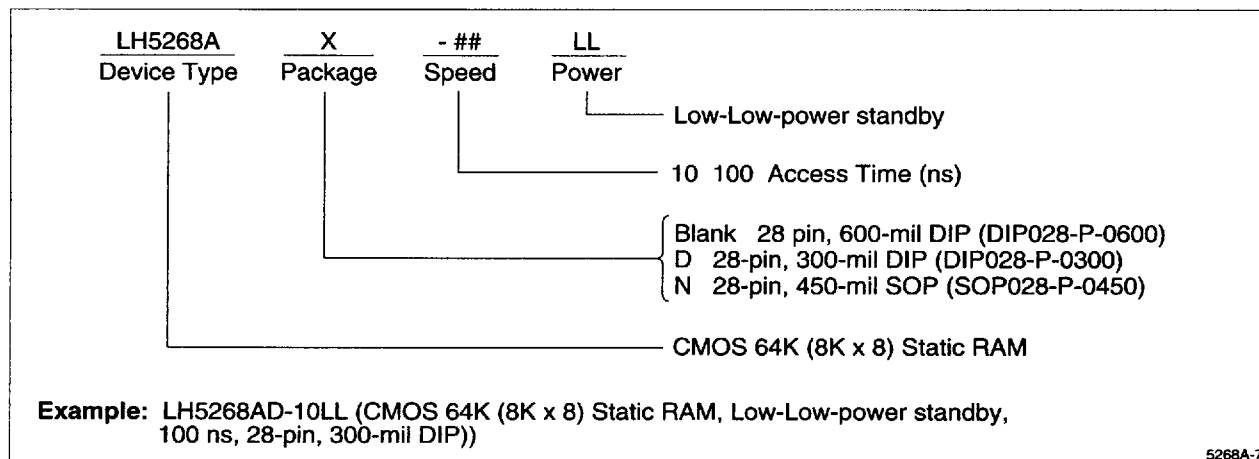


DIMENSIONS IN MM [INCHES]	MAXIMUM LIMIT	
	MINIMUM LIMIT	

28SOP

28-pin, 450-mil SOP

ORDERING INFORMATION



5268A-7